



Material Content Data Sheet



Sales Product Name		BSS84P H6327		Issued		29. August 2013		
MA#		MA001097556						
Package		PG-SOT23-3-5		Weight*		9.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.007	0.07		717	
	non noble metal	tin	7440-31-5	0.002	0.02		185	
	inorganic material	silicon	7440-21-3	0.076	0.81	0.90	8125	9027
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		970	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		323	
wire	non noble metal	copper	7440-50-8	3.000	32.19	32.33	321912	323270
	non noble metal	copper	7440-50-8	0.008	0.09	0.09	889	889
	encapsulation	organic material	carbon black	1333-86-4	0.058	0.62		6202
encapsulation	plastics	epoxy resin	-	1.243	13.34		133353	
	inorganic material	silicondioxide	60676-86-0	4.480	48.06	62.02	480689	620244
leadfinish	non noble metal	tin	7440-31-5	0.150	1.61	1.61	16055	16055
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30515	30515
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com